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- (71) **Applicant: FUJIFILM ELECTRONIC MATERIALS U.S.A., INC.** [US/US]; 80 Circuit Drive, N. Kingstown, Rhode Island 02852 (US).
- (72) **Inventor: DE, Binod B.**; 3 Stanley Street, Attleboro, Massachusetts 02703 (US).

(74) **Agent: WEFERS, Marc M.** et al.; Fish & Richardson P.C., P.O. Box 1022, Minneapolis, Minnesota 55440-1022 (US).

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(54) **Title:** DIELECTRIC FILM-FORMING COMPOSITION

(57) **Abstract:** This disclosure relates to a dielectric film-forming composition that includes (a) at least one meth(acrylate)-containing polyphenylene ether resin and (b) at least one second resin selected from the group consisting of: i) at least one fully imidized polyimide polymer; ii) at least one polyamic acid ester; iii) at least one cyclized polydiene resin; and iv) a mixture of a cyclized polydiene resin and a cyanate ester compound.



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